

In the Specification

Please amend paragraph [0037] as follows.

[0037] Referring again to FIG. 9, the connection bars 78 and 79 intersect at a point between the four die 70-76. The first (inner) rows of terminals are attached to the connection bars 78, 79 through grooved connection interfaces 77 in a manner such as that shown in the drawing. The leadframe panel 60 is preferably formed from a sheet of conductive metal having a good thermal conductivity, such as copper. The leadframe panel 60 may be formed by a stamping method, however, for more complex and higher density leadframes, a chemical etching method is preferred. As is understood by those of skill in the art, the etching method uses an artwork mask to define the detailed pattern of the leadframe and then the unmasked portion of the metal is etched away. A plating mask is used to mask out no-plating zones, if any, and then the unmasked portions are plated with metal layers with a plating process. Rinsing and cleaning steps are performed between processes. Such masking, etching, plating, rinsing and cleaning processes are well known to those of skill in the art.